



TS461-TS462-TS464

Output Rail-to-Rail Operational Amplifiers

- High dynamic features
- Large output swing ($\pm 2.4V$ @ $V_{CC} = \pm 2.5V$)
- Low noise level: $4nV/\sqrt{Hz}$
- Low distortion: 0.003%
- Operating range: 2.7V to 10V
- Available in SOT23-5 micropackage

Description

The TS46x are a family of operational amplifiers able to operate with voltages as low as $\pm 1.35V$ and to reach a minimum of $\pm 2V_{pp}$ of output swing when supplied with $\pm 2.5V$.

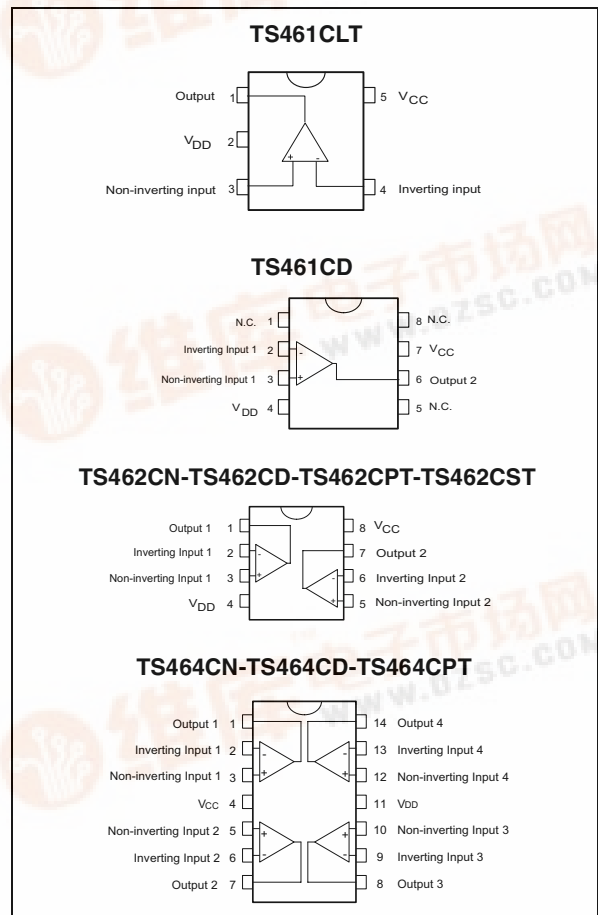
This device is well-suited for all kinds of portable and battery-supplied equipment, where low noise and low distortion are key requirements.

The TS461/2/4 offer excellent output rail-to-rail performance at an attractive cost.

Applications

- Sound cards
- PDA
- CD players
- Recording equipment
- Multimedia
- Microphone preamplifiers

Pin Connections (top view)



Order Codes

Part Number	Temperature Range	Package	Packaging	Marking
TS461CLT	-20°C, +70°C	SOT23-5L	Tape & Reel	K105
TS461CD/CDT		SO-8	Tube or Tape & Reel	
TS462CST		mini SO-8	Tape & Reel	
TS462CPT		TSSOP-8 (Thin Shrink Outline Package)	Tape & Reel	
TS462CN		DIP8	Tube	
TS462CD/CDT		SO-8	Tube or Tape & Reel	
TS464CPT		TSSOP-14 (Thin Shrink Outline Package)	Tape & Reel	
TS464CN		DIP14	Tube	
TS464CD/CDT		SO-14	Tube or Tape & Reel	

1 Absolute Maximum Ratings

Table 1: Key parameters and their absolute maximum ratings

Symbol	Parameter	Value	Unit
VCC	Supply voltage ¹	12	V
V _{id}	Differential Input Voltage ²	±VCC	V
V _{in}	Input Voltage Range	V _{dd} -0.3 to V _{cc} +0.3	V
T _{oper}	Operating Free Air Temperature Range	-20 to +70	°C
T _{std}	Storage Temperature Range	-65 to +150	°C
T _j	Maximum Junction Temperature	150	°C
R _{thja}	Thermal Resistance Junction to Case ³ SOT23-5 SO8 SO14 TSSOP8 TSSOP14	250 125 103 120 100	°C/W
ESD	HBM: Human Body Model ⁴	2	kV
	MM: Machine Model ⁵	200	V
	CDM: Charged Device Model	1.5	kV
	Lead Temperature (soldering, 10sec)	250	°C

1) All voltages values, except differential voltage are with respect to network group terminal.

2) Differential voltages are non-inverting input terminal with respect to the inverting input terminal.

3) Short-circuits can cause excessive heating and destructive dissipation.

4) Human body model, 100pF discharged through a 1.5kΩ resistor into pin of device.

5) Machine model ESD, a 200pF cap is charged to the specified voltage, then discharged directly into the IC with no external series resistor (internal resistor < 5Ω), into pin to pin of device.

Table 2: Operating conditions

Symbol	Parameter	Value	Unit
VCC	Supply Voltage	2.7 to 10	V
V _{icm}	Common Mode Input Voltage Range	V _{DD} +1.15 to V _{CC} - 1.15	V
T _{oper}	Operating Free Air Temperature Range	-20 to +70	°C

2 Electrical Characteristics

Table 3: $V_{CC} = 2.5V$, $V_{DD} = -2.5V$, $T_{amb} = 25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{io}	Input Offset Voltage $T_{min.} \leq T_{amb} \leq T_{max.}$		1	5 7	mV
ΔV_{io}	Input Offset Voltage Drift $V_{icm} = 0V$, $V_o = 0V$		5		$\mu V/^{\circ}C$
I_{io}	Input Offset Current $V_{icm} = 0V$, $V_o = 0V$ $T_{min.} \leq T_{amb} \leq T_{max.}$		10	150 200	nA
I_{ib}	Input Bias Current $V_{icm} = 0V$, $V_o = 0V$ $T_{min.} \leq T_{amb} \leq T_{max.}$		200 200	750 1000	nA
V_{icm}	Common Mode Input Voltage Range	-1.35		1.35	V
CMR	Common Mode Rejection Ratio $V_{icm} = \pm 1.35V$	60	85		dB
SVR	Supply Voltage Rejection Ratio $V_{cc} = \pm 2V$ to $\pm 3V$	60	70		dB
A_{vd}	Large Signal Voltage Gain $R_L = 2k\Omega$	70	80		dB
V_{OH}	High Level Output Voltage $R_L = 2k\Omega$	2	2.4		V
V_{OL}	Low Level Output Voltage $R_L = 2k\Omega$		-2.4	-2	V
I_{CC}	Supply Current, per amplifier Unity gain - no load		2	2.8	mA
GBP	Gain Bandwidth Product $f = 100kHz$ $R_L = 2k\Omega$, $C_L = 100pF$	8.5	12		MHz
SR	Slew Rate $A_V = 1$, $V_{in} = \pm 1V$	2.8	4		V/ μs
en	Equivalent Input Noise Voltage $f = 100kHz$		4		$\frac{nV}{\sqrt{Hz}}$
THD	Total Harmonic Distortion $f = 1kHz$, $A_V = -1$ $R_L = 10k\Omega$		0.003		%

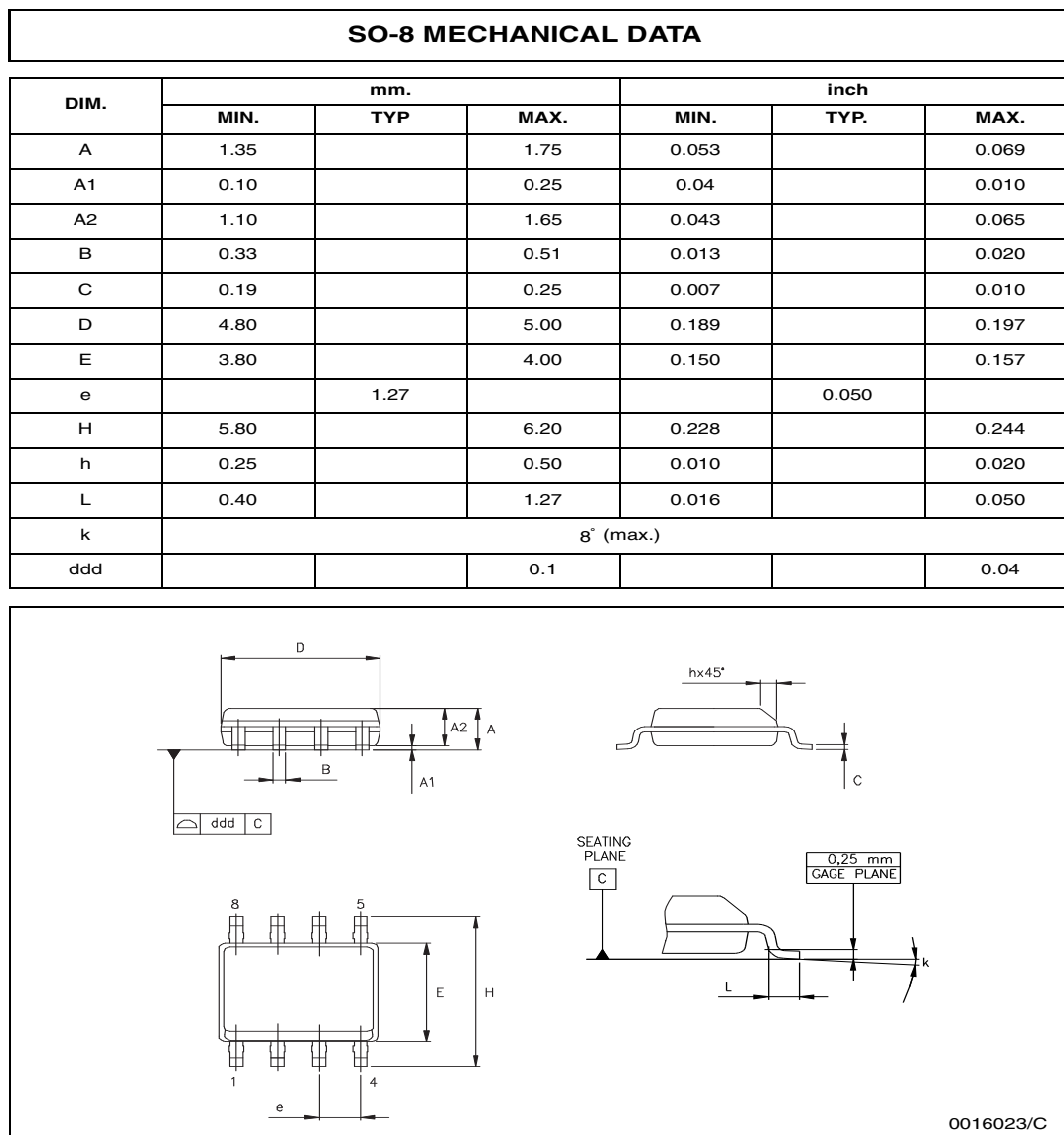
3 Package Mechanical Data

3.1 SOT23-5L package

SOT23-5L MECHANICAL DATA						
DIM.	mm.			mils		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	0.90		1.45	35.4		57.1
A1	0.00		0.15	0.0		5.9
A2	0.90		1.30	35.4		51.2
b	0.35		0.50	13.7		19.7
C	0.09		0.20	3.5		7.8
D	2.80		3.00	110.2		118.1
E	2.60		3.00	102.3		118.1
E1	1.50		1.75	59.0		68.8
e		0.95			37.4	
e1		1.9			74.8	
L	0.35		0.55	13.7		21.6

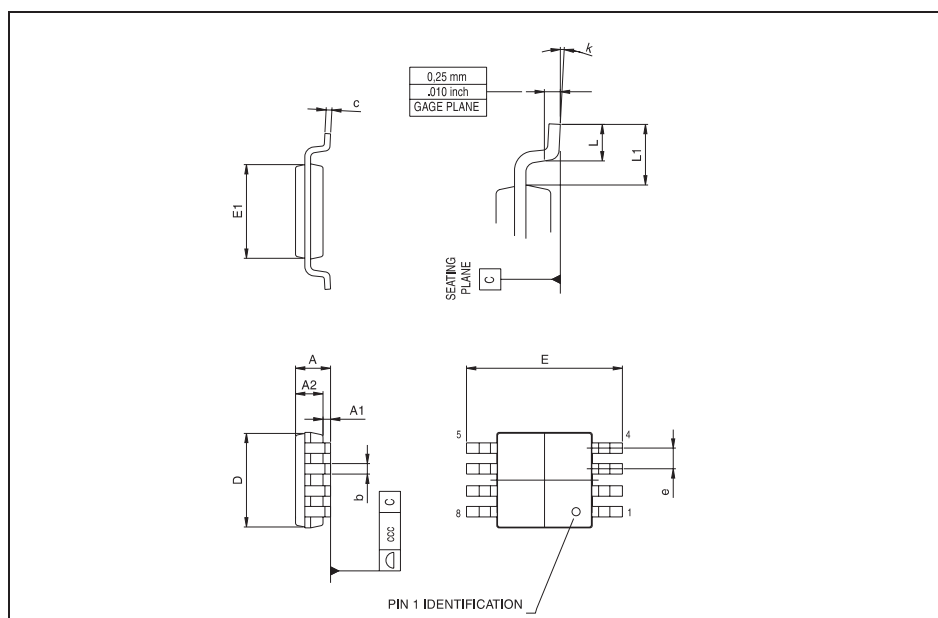
The diagram illustrates the mechanical dimensions of the SOT23-5L package. The left view is a side profile showing dimensions A (total width), A1 (lead thickness), A2 (lead width), C (lead height), and L (package height). The right view is a top-down perspective showing dimensions D (package width), E (package length), E1 (lead length), e (pitch), e1 (total pitch), and b (lead width).

3.2 SO-8 package



3.3 Mini SO-8 package

miniSO-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.1			0.043
A1	0.05	0.10	0.15	0.002	0.004	0.006
A2	0.78	0.86	0.94	0.031	0.031	0.037
b	0.25	0.33	0.40	0.010	0.13	0.013
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	4.75	4.90	5.05	0.187	0.193	0.199
E1	2.90	3.00	3.10	.0114	0.118	0.122
e		0.65			0.026	
K	0°		6°	0°		6°
L	0.40	0.55	0.70	0.016	0.022	0.028
L1			0.10			0.004



3.4 TSSOP8 package

TSSOP8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.008
D	2.90	3.00	3.10	0.114	0.118	0.122
E	6.20	6.40	6.60	0.244	0.252	0.260
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.65			0.0256	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1			0.039	

0079397/D

3.5 DIP8 package

Plastic DIP-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A		3.3			0.130	
a1	0.7			0.028		
B	1.39		1.65	0.055		0.065
B1	0.91		1.04	0.036		0.041
b		0.5			0.020	
b1	0.38		0.5	0.015		0.020
D			9.8			0.386
E		8.8			0.346	
e		2.54			0.100	
e3		7.62			0.300	
e4		7.62			0.300	
F			7.1			0.280
I			4.8			0.189
L		3.3			0.130	
Z	0.44		1.6	0.017		0.063

P001F

3.6 TSSOP14 package

TSSOP14 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

PIN 1 IDENTIFICATION

0080337D

3.7 DIP14 package

Plastic DIP-14 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

The mechanical drawing illustrates the dimensions of a Plastic DIP-14 package. The top view shows the package body with pins on all four sides. Key dimensions labeled include: **a1** (pin thickness), **B** (pin pitch), **b** (pin width), **b1** (pin thickness), **D** (package width), **E** (package length), **e** (pin spacing), **e3** (total pin length), **F** (pin height), **I** (pin length), **L** (package thickness), and **Z** (pin offset). The bottom view shows the package with pins numbered 1 through 14. The side view shows the package profile with dimensions **E** and **b1**.

P001A

3.8 SO-14 package

SO-14 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					

PO13G

4 Revision History

Date	Revision	Description of Changes
January 2002	1	First Release
March 2005	2	Modifications on AMR Table 1 on page 2 (explanation of Vid and Vi limits)

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